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(54) **VARIABLE TOPOGRAPHY HEAT SINK FINS**

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**ABSTRACT**

Methods, systems, and devices for providing computer-implemented services are disclosed. To provide the computer-implemented services, hardware components that generate heat may be used. To manage the heat generated by the hardware components, a heat sink assembly may be used. The heat sink assembly may include features for adjusting its shape and/or size to accommodate other nearby components. By accommodating other components, the heat sink assembly may be used in spaces that would otherwise be unusable for thermal dissipation purposes due to the risk of mechanical interference between the heat sink assembly and the other components.

